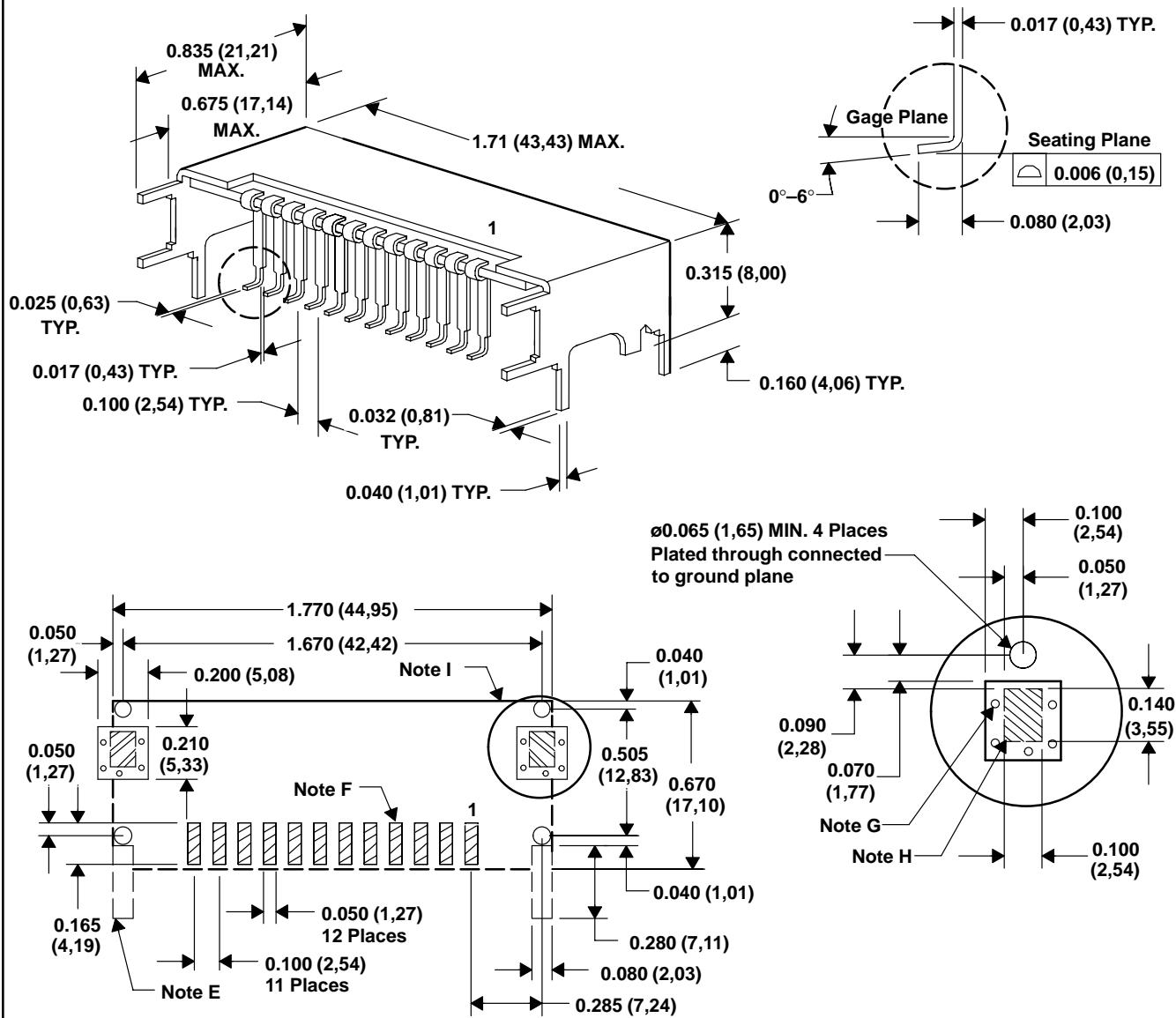


## EPK (R-MSIP-G12)

## METAL SINGLE-IN-LINE MODULE

## SUFFIX C



4203206/B 06/02

NOTES:

- A. All linear dimensions are in inches (mm).
- B. This drawing is subject to change without notice.
- C. 2 place decimals are  $\pm 0.030$  ( $\pm 0.76$  mm).
- D. 3 place decimals are  $\pm 0.010$  ( $\pm 0.25$  mm).
- E. Recommended mechanical keep-out area.
- F. Power pin connections should utilize two or more vias per input, ground and output pin.

- G. Vias are recommended to improve copper adhesion.
- H. Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to ground plane.
- I. Case outline reference.



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